



Material Content Data Sheet



Sales Product Name		IFX20001MB V50		Issued		29. August 2013		
MA#		MA000633850						
Package		PG-SCT595-5-1		Weight*		13.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.294	2.12	2.12	21155	21155
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		436	
	non noble metal	chromium	7440-47-3	0.018	0.13		1307	
	non noble metal	copper	7440-50-8	6.019	43.36	43.54	433721	435551
wire	noble metal	gold	7440-57-5	0.029	0.21	0.21	2064	2064
encapsulation	organic material	carbon black	1333-86-4	0.055	0.40		3973	
	plastics	brominated resin	-	0.069	0.50		4967	
	inorganic material	antimonytrioxide	1309-64-4	0.138	0.99		9933	
	plastics	epoxy resin	-	1.254	9.04		90391	
	inorganic material	silicondioxide	60676-86-0	5.376	38.74	49.67	387388	496652
leadfinish	non noble metal	tin	7440-31-5	0.335	2.42	2.42	24170	24170
plating	noble metal	silver	7440-22-4	0.142	1.02	1.02	10197	10197
glue	plastics	epoxy resin	-	0.025	0.18		1787	
	noble metal	silver	7440-22-4	0.117	0.84	1.02	8424	10211
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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